

PATENTPre
S/A And
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ACG**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE****In re Application of:**

Salman Akram

Serial No.: 09/388,031**Filed:** September 1, 1999**For:** METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME**Examiner:** To be assigned**Group Art Unit:** 2812**Attorney Docket No.:** 3442US (96-428)**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

August 1, 2000
Date of Deposit

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Joseph A. Walkowski
Typed/printed name of person whose signature is contained above

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PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to the examination of the claims on the merits in the above-referenced application, please amend this application as follows:

IN THE SPECIFICATION:

On page 2, line 18, insert --and-- after "features";

On page 4, line 3, delete the comma after "resistivity" and insert commas after "and" and "therefore";